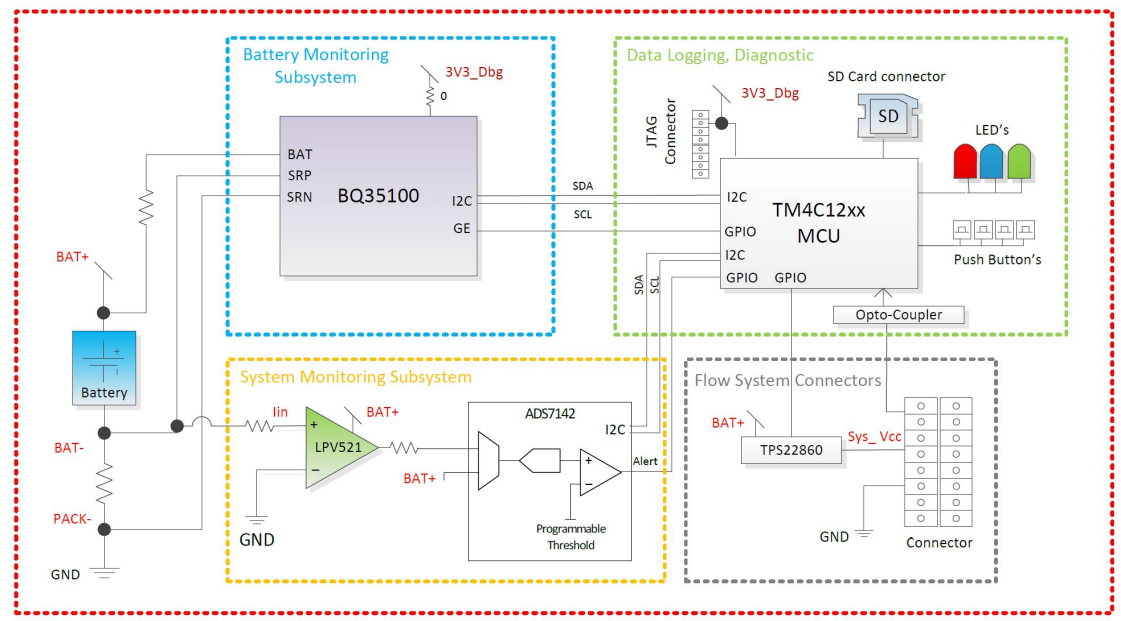


Revision History				
Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A

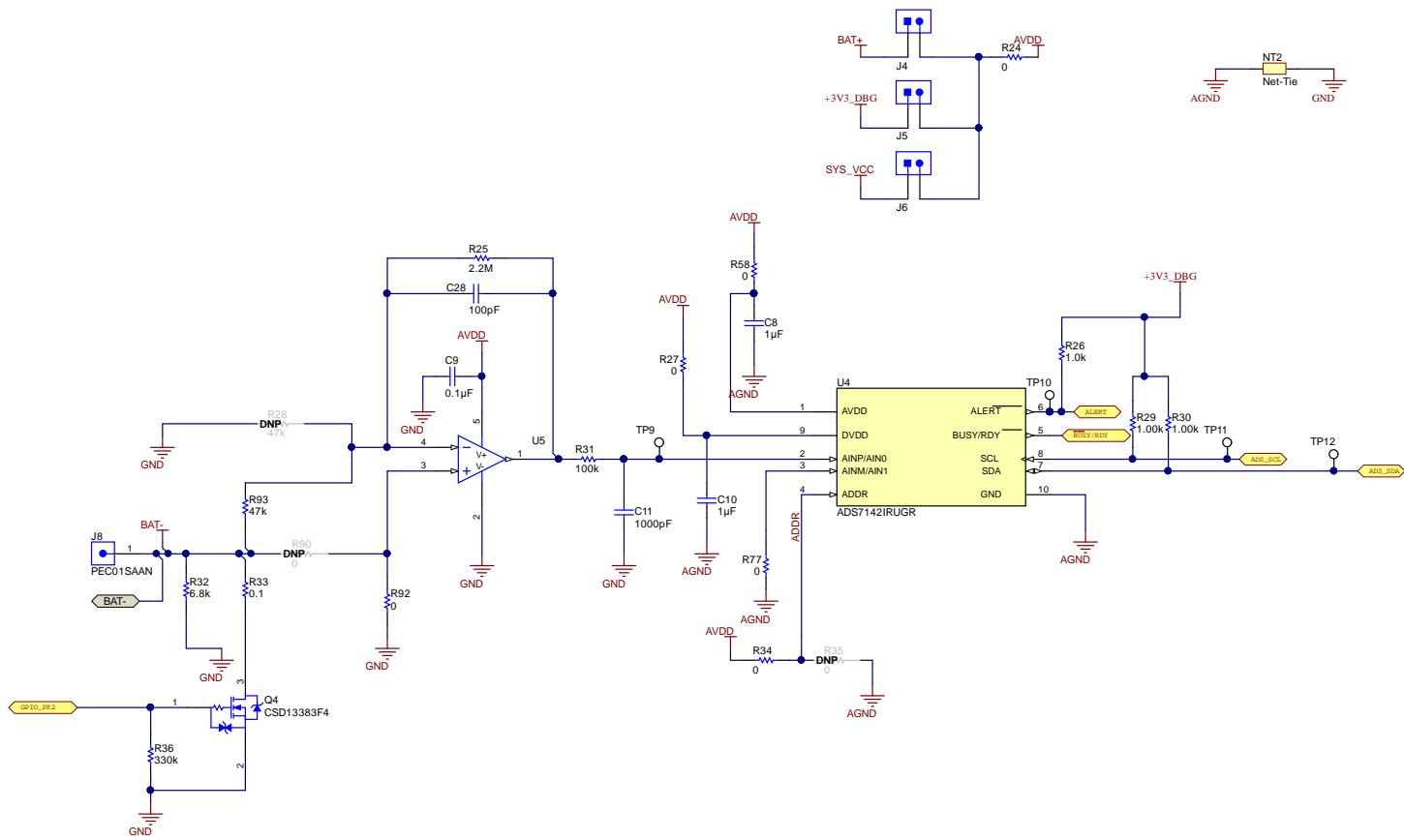


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Orderable: EVM, orderable	Designed for Public Release	Mod. Date: 7/9/2018
TID #: TIDA-01546	Project Title: Change in menu Project Options/Parameters	
Number: TIDA-01546 Rev: E2	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: TIDA_01546 Inverting	Sheet: 1 of 3
Drawn By:	File: TIDA-01546 Proj_CoverSheet_SchDoc	Size: B
Engineer: Enter name of project lead	Contact: http://www.ti.com/support	

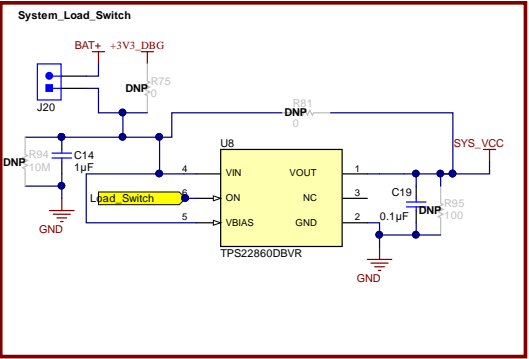
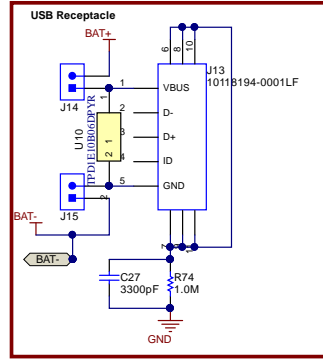
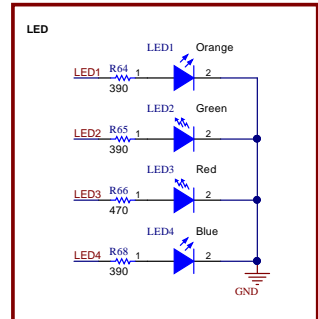
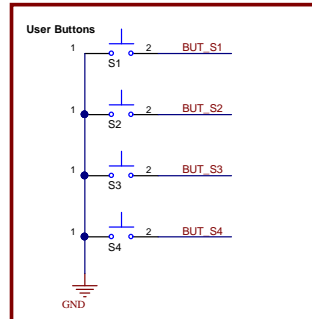
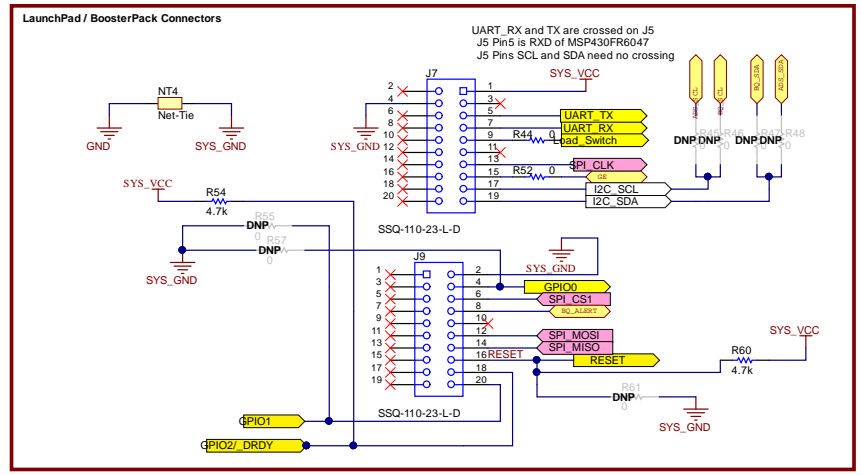
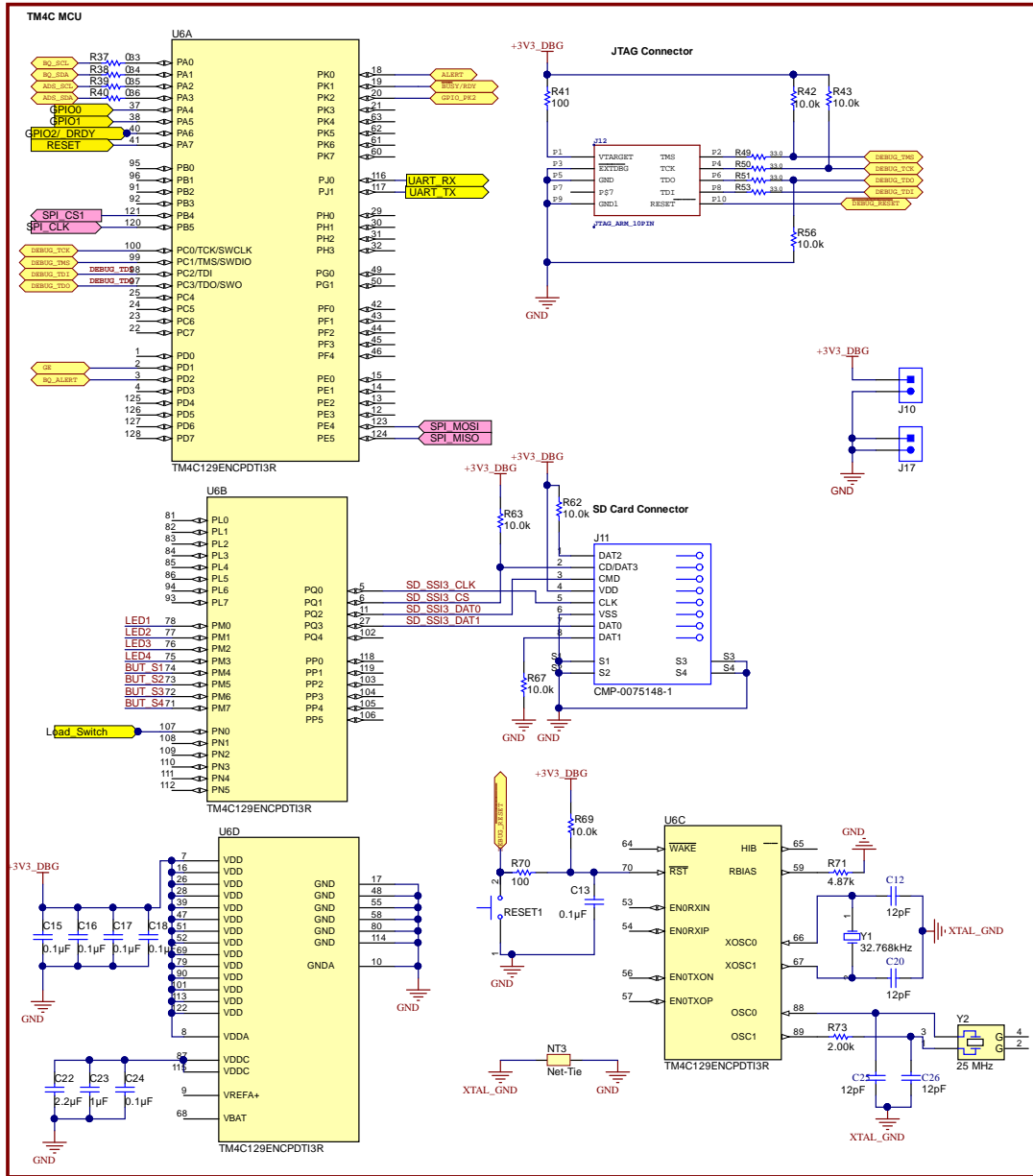


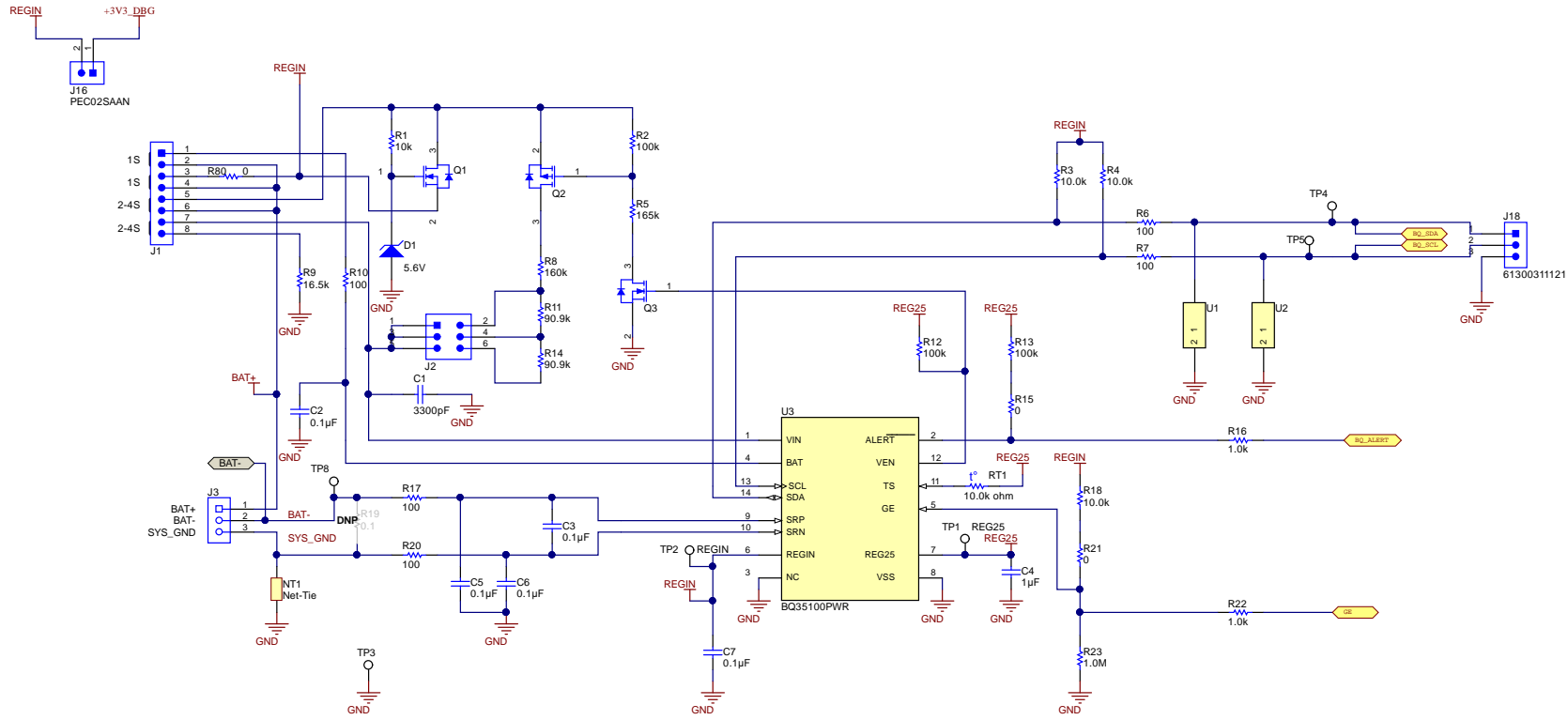


Orderable: EVM_orderable	Designed for: Public Release	Mod. Date: 4/30/2018
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Number: TIDA-01546 Rev: E2	Sheet Title:	
Rev: Version control disabled	Assembly Variant: TIDA_01546_Inverting	Sheet: 2 of 3
Drawn By:	File: TIDA-01546_Proj_SysMonitoring_SchDoc	Size: B
Engineer: Enter name of project lead	Contact: http://www.ti.com/support	



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Orderable: EVM_orderable	Designed for: Public Release	Mod. Date: 4/30/2018
TID #: TIDA-01546	Project Title: Change in menu Project Options/Parameters	
Number: TIDA-01546 Rev: E2	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: TIDA_01546_Inverting	Sheet: 2 of 3
Drawn By:	File: TIDA-01546_Proj_BatMonitoring_SchDoc	Size: B
	Contact: http://www.ti.com/support	



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DNP
FD1 DNP
FD2 DNP
FD3

PCB Number: TIDA-01546
PCB Rev: E2

PCB LOGO
Texas Instruments PCB LOGO PCB LOGO

Variant/Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

LBL1
PCB Label
Size: 0.65" x 0.20"

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Orderable: EVM_orderable	Designed for Public Release	Mod. Date: 10/18/2017
TID #: TIDA-01546	Project Title: Change in menu Project	Project Options/Parameters
Number: TIDA-01546 Rev: E2	Sheet Title:	Sheet: 3 of 3
BYN Rev: Version control disabled	Assembly Variant: TIDA_01546_Inverting	File: TIDA-01546_Proj_EVM_Hardware_SchDoc
Drawn By:	Engineer: Enter name of project lead	Contact: http://www.ti.com/support

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